

ZHX1010

SIR Transceiver

Product Specification

PS015105-0702



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Table of Contents

| Description |
|---|
| Features |
| Pin Descriptions |
| TAB 2 TXD Transmit Data 2 RXD Receive Data 3 SD Shutdown 3 LEDA IRED Driver Anode 3 |
| Recommended Application Circuit 4 |
| Electrical and Timing Specifications 5 |
| Transceiver Performance |
| Mechanical Drawings 8 |
| ZHX1010 Soldering and Cleaning Recommendations9Reflow Soldering9Manual Soldering9Cleaning10 |
| ZHX1010 Packing, Storage, and Baking Recommendations10Storage10Baking10Moisture Prevention Guidelines11 |
| Taping Specifications |
| Ordering Information |
| Customer Feedback Form14Customer Information14Product Information14Return Information14Problem Description or Suggestion14 |

List of Figures

| Figure 1. | Application Block Diagrams |
|-----------|---|
| Figure 2. | Typical Radiant Intensity (I _E) Versus Angle |
| Figure 3. | Typical Irradiance (Ee) Versus Angle at BER = 1 in 10 ⁻⁸ |
| Figure 4. | ZHX1010 Mechanical Drawing 8 |
| Figure 5. | Temperature Profile at the Top Surface of ZHX1010 9 |
| Figure 6. | ZHX1010 Transceiver Packaging |
| Figure 7. | ZHX1010 Reel Dimensions (Unit: mm) |
| Figure 8. | ZHX1010 Tape Dimensions and Configuration (Unit: mm) 13 |

List of Tables

| Table 1. | Pin Out for the ZHX1010 SIR Transceiver | 2 |
|----------|---|---|
| Table 2. | Absolute Maximum Ratings | 5 |
| Table 3. | Recommended Operating Conditions | 5 |
| Table 4. | Electrical Characteristics | 5 |

Description

The ZiLOG ZHX1010 SIR transceiver is the ideal choice for applications in today's ultra-compact and power-conscious portable products, such as mobile phones, digital cameras, portable printers, handheld computers, or personal data assistants (PDA). Designed to support the SIR (serial infrared) Infrared Data Association (IrDA) Data standard (2.4–115.2 Kbps, 1 meter minimum), LocalTalkTM, and Sharp ASKTM modes, the transceiver combines an infrared emitting diode (IRED), a PIN photodiode detector, a digital AC coupled IRED driver, and a receiver/decoder with noise discrimination circuitry in a single, miniature package.

The ZiLOG ZHX1010 SIR transceiver provides an efficient implementation of the IrDA-Data standard in a small footprint format. Application circuit space is also minimized, as only two external resistors and one capacitor are needed to complete the IrDA transceiver solution. The ZHX1010 SIR transceiver meets the IEC825-Class 1 Eye Safety limits.

An external shield minimizes radio frequency interference (RFI) and electromagnetic interference (EMI) problems.

Features

- Compliant to IrDA SIR Specifications (2.4–115.2 Kbps, 1 meter minimum)
- Wide supply voltage range, 2.4 to 5.5 V
- Low power, 90 μA (typical) at 3 V
- Slim-shield option: 9.9 mm long x 3.7 mm wide x 4.0 mm high
- Two external components: one resistor and one capacitor
- Extended operating temperature range (–30 °C to +85 °C)
- Meets the IEC 825-1 Class 1 Eye Safety Specifications

Pin Descriptions

The ZHX1010 SIR transceiver uses the pins listed in Table 1. The pins are described in this section.

Table 1. Pin Out for the ZHX1010 SIR Transceiver

| Pin | Name | Function | I/O |
|-----|-----------------|-----------------------|-----|
| 1 | LEDA | IRED anode | _ |
| 2 | TXD | Transmitter input | I |
| 3 | RXD | Receiver output | 0 |
| 4 | SD | Enables shutdown mode | I |
| 5 | V _{CC} | Supply voltage | _ |
| 6 | GND | Ground | _ |
| _ | TAB | Shield ground | _ |

V_{CC} Positive Supply

(Power)

Connect to positive power supply (2.4–5.5 V).

Place a .33- μF ceramic bypass capacitor (optional) as close as possible to the V_{CC} pin.

GND Ground

(Power)

Connect to ground of the power supply. A solid ground plane is recommended for proper operation.

TAB

(Shield)

The Shield tab must be soldered to the ground plane.

TXD Transmit Data

(Input, active high)

This CMOS input is used to transmit serial data.

This input has an internal pull-down resistor that is disabled (open-circuited) during shutdown. TXD has integrated digital AC coupling that prevents inadvertent "always on" IREDs; therefore, no external AC coupling components are required for input signals between GND and $V_{\rm CC}$.

RXD Receive Data

(Output, active low).

This output indicates received serial data. It is a tri-state, slew rate controlled CMOS output (tri-stated during shutdown) driver capable of driving a standard CMOS or LSTTL load. No external resistor is required.

SD Shutdown

(Input, active high)

This input is used to place the integrated circuit into shutdown mode. Maximum current draw in shutdown mode is 1 μ A. Module shutdown current might be limited by the choice of capacitor used from V_{CC} to ground. A 0.1-mF ceramic capacitor with very high DC impedance (1–10 G ohm) is required to minimize shutdown current to nanoamp levels. During shutdown, the output is tri-stated, and the TXD input pull-down resistor is disabled (open circuited).

LEDA IRED Driver Anode

(Output, active low).

This output is internally connected to the IRED anode and is connected to LEDA through a current limiting resistor. Current to the IRED must be limited to a maximum of 500 mA (20% duty cycle maximum). The maximum voltage on this pad is limited to +5.5 volts or $V_{\rm CC}$.

Recommended Application Circuit

Figure 1 shows applications for the ZHX1010 SIR transceiver.

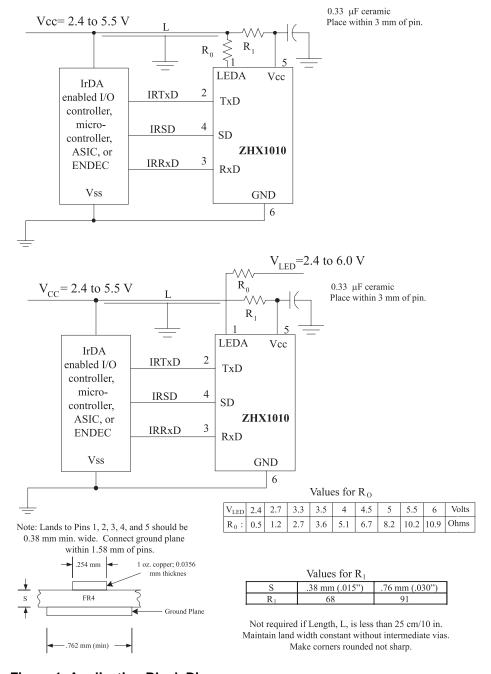


Figure 1. Application Block Diagrams

Electrical and Timing Specifications

Table 2 through Table 4 present the electrical and timing specifications for the ZHX1010 SIR transceiver.

Table 2. Absolute Maximum Ratings

| Parameter | Symbol | Minimum | Maximum | Unit | Comment |
|--------------------------------|------------------|-------------|---------|------|----------------|
| Supply Voltage | Vcc | -0.3 | 6.0 | V | |
| Power Dissipation | P _D | | 500 | mW | |
| Junction Temperature | TJ | | 125 | °C | |
| Storage Temperature | | - 55 | 85 | °C | |
| Solder Temperature (10 seconds | s) | | 230 | °C | |
| IRED Current | I _{LED} | | 700 | mA | 20% duty cycle |
| Any Pin Voltage | | -0.5 | Vcc+0.5 | V | |

Table 3. Recommended Operating Conditions

| Parameter | Symbol | Minimum | Maximum | Unit |
|-------------------------------|----------------|---------|---------|------|
| Supply Voltage | Vcc | 2.4 | 5.5 | V |
| Ambient Operating Temperature | T _A | -30 | 85 | °C |

Table 4. Electrical Characteristics

| Parameter | Condition | Min | Typical | Max | Unit |
|--|---|-----|---------|-----|-------|
| Operating Current (I _{CC}) | No load, SD = TXD = "0" 3.0 V; T = 25 °C | | 90 | 150 | μΑ |
| Shutdown Current (I _{SD}) | SD = "V _{CC} ", Photodiode input current = 0 | | | 1 | μΑ |
| Peak Current Transmit (I _{LED}) Transmitter | | | 300 | | mA |
| Radiant Intensity (I _E)(±15°) | LED Peak I _F = 300 mA, TXD Logic "High" | 40 | | 100 | mW/sr |
| Radiant Intensity | TXD Logic "Low" | | | 0.3 | mW/sr |
| Angle of Half Intensity | | | 20 | | 0 |



6

Table 4. Electrical Characteristics (Continued)

| Parameter | Condition | Min | Typical | Max | Unit |
|---|--|-----------------------|----------|-------------------------|--------------------|
| Optical Rise/Fall time | | | 40 | | ns |
| Peak Wavelength | | 850 | 875 | 900 | nm |
| Optical Overshoot | | | | 3 | % |
| Receiver | | | | | |
| Detection Threshold Irradiance | <u>+</u> 15 ° | | 2 | 3 | μW/cm ² |
| Overload Irradiance | | 500 | | | μW/cm ² |
| Sunlight Ambient Rejection | No modulation | 500 | | | μW/cm ² |
| Digital Input/Output | | | | | |
| Input High (Logic 1) Voltage, V _{IH} | TXD, SD | 0.6 V _{CC} | | V _{CC} + 0.5 V | V |
| Input Low (Logic 0) Voltage, V _{IL} | TXD, SD | -0.5 | | 0.2 V _{CC} | V |
| Output High (Logic 1) Voltage, V _{OH} | RXD/ = -250 mA @ 1.8 V | 2.2 | | | V |
| Output Low (Logic 0) Voltage, V _{OL} | RXD/ = 1 mA | | | 0.4 | V |
| Output Leakage (RXD, Anode) | SD = "1" | -1 | | +1 | μΑ |
| Input Leakage | SD, TXD = "0" | -1 | | +1 | μΑ |
| Input Current | TXD = "1", SD = "0" | 4 | | 100 | μΑ |
| AC Parameters | (C _{LOAD} = 25 pF) | | | | |
| Transmit Output Pulse Width | TXD = 1 > 200 ms | 18 | | 150 | μs |
| Recovery Delay from Shutdown to Full Sensitivity (T _{RECOVERY}) | SD = "1" →"0" | | | 200 | μs |
| Receiver Latency (T _L) | | | 100 | | μs |
| Rise Time (T _R) | V _{CC} = 1.8–5.5 V | | 100 | | ns |
| Fall Time (T _F) | V _{CC} = 1.8–5.5 V | | 100 | | ns |
| Pulse Width (T _W) (RXD) | $I_{DET} = 1 \mu A$, 1.6-ms pulse | 1.1 | 1.6 | 3.9 | μs |
| Pulse Jitter (T _J) (RXD) | Irradiance = 3.5 mW/cm ² – 500 mW/cm ² | | | 400 | ns |
| Pulse Delay (T _D) (RXD) | Irradiance = 3.5 mW/cm ² - 500 mW/cm ² | | | 1.8 | μs |
| Unless otherwise noted: V _{CC} /LEDA= | =2.4 V to 5.5 V, GND= 0 V, T, | _A = −30 °C | to 85 °C | | |

Transceiver Performance

Figure 2 and Figure 3 show the performance of the ZHX1010 SIR transceiver.

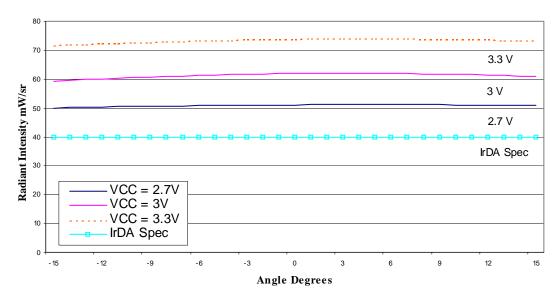


Figure 2. Typical Radiant Intensity (I_F) Versus Angle

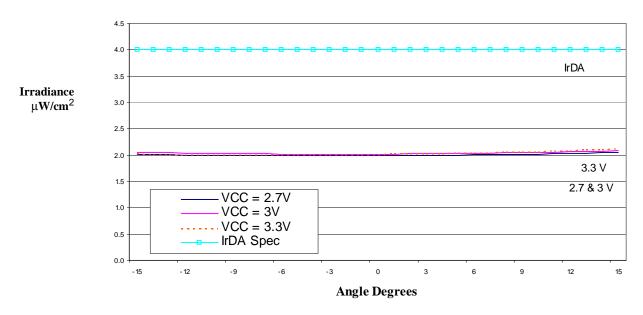
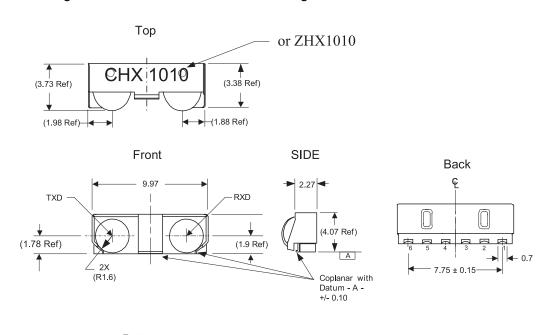
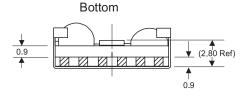


Figure 3. Typical Irradiance (Ee) Versus Angle at BER = 1 in 10^{-8}

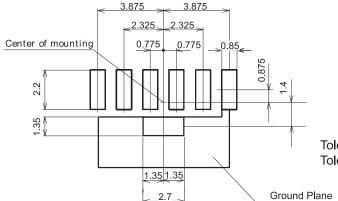
Mechanical Drawings

Figure 4 shows the mechanical drawings for the ZHX1010 SIR transceiver.





Note: The Shield tab must be soldered to the gound plane.



| PIN | FUNCTION | PIN | FUNCTION |
|-----|----------|-----|----------|
| 1 | LEDA | 4 | SD |
| 2 | TXD | 5 | VCC |
| 3 | RXD | 6 | GND |
| | | _ | TAB |

Tolerances for 0.x or 0.xx are +/- 0.25 mm Tolerance for 0.xxx is +/- 0.13 mm

Figure 4. ZHX1010 Mechanical Drawing

ZHX1010 Soldering and Cleaning Recommendations

Follow these recommendations to maintain the performance of the ZHX1010 SIR transceiver.

Reflow Soldering

• Reflow soldering paste is recommended:

Melting temperature: 178 °C ~ 192 °C

Composition: Sn 63%, Pb 37%

- The recommended thickness of the metal mask is between 0.2 mm and 0.25 mm for screen printing.
- Number of soldering times: 2 times maximum
- The temperature profile at the top surface of ZHX1010, shown in Figure 5, is recommended.

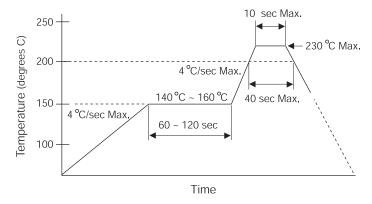


Figure 5. Temperature Profile at the Top Surface

Manual Soldering

- Use 63/37 or silver solder.
- Use a soldering iron of 25 W or smaller. Adjust the temperature of the soldering iron below 300 °C.
- Finish soldering within 3 seconds.
- Handle only after ZHX1010 has cooled off.

Cleaning

Perform cleaning after soldering under the following conditions:

- Cleaning agent: Alcohol
- Temperature and time: 30 seconds below 50 °C or 3 minutes below 30 °C
- Ultrasonic cleaning: Below 20 W

ZHX1010 Packing, Storage, and Baking Recommendations

Follow these recommendations to maintain the performance of the ZHX1010 SIR transceiver.

Storage

To avoid moisture absorption, ZHX1010 reels must remain in the original, unopened moisture-proof packing. Parts must be soldered within 48 hours after unpacking. Reels that have been unpacked, but will not be soldered within 48 hours, must be stored in a desiccator.

Baking

Parts that have been stored over 12 months or unpacked over 48 hours must be baked under the following guidelines.

Reels

60 °C for 48 hours or more

Loose Parts

100 °C for 4 hours or more

or

125 °C for 2 hours or more

or

• 150 °C for 1 hour or more

Moisture Prevention Guidelines

In order to avoid moisture absorption during transportation and storage, ZHX1010 reels are packed in aluminum envelopes (see Figure 6) that contain a desiccant with a humidity indicator. While this packaging is an impediment to moisture absorption, it is by no means absolute, and no warranty is implied. The user should store these parts in a controlled environment to prevent moisture entry. Please read the label on the aluminum bag for indicator instructions.

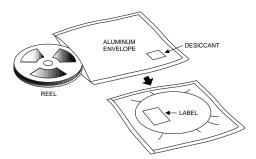


Figure 6. ZHX1010 Transceiver Packaging

Taping Specifications

Figure 7 and Figure 8 show the reel dimensions and tape dimensions and configuration for the ZHX1010.

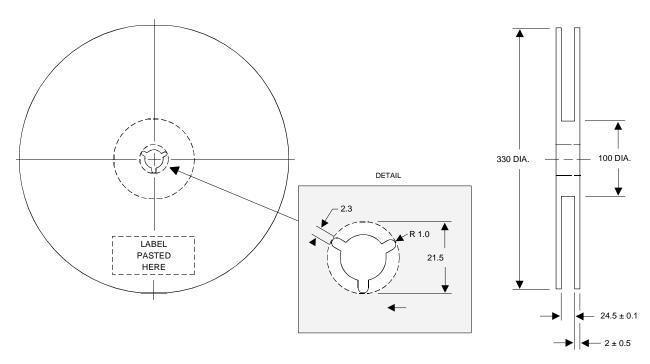


Figure 7. ZHX1010 Reel Dimensions (Unit: mm)

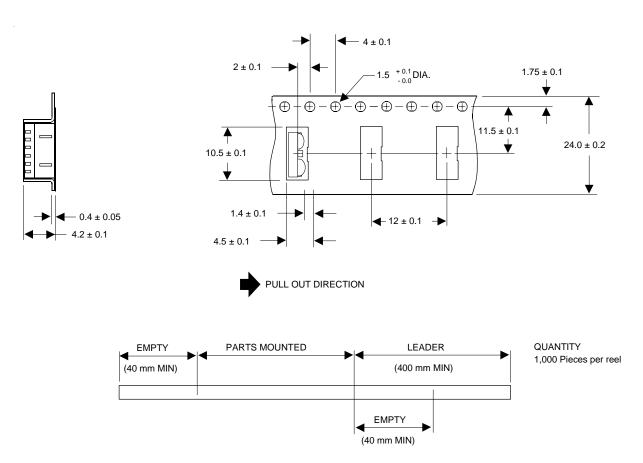


Figure 8. ZHX1010 Tape Dimensions and Configuration (Unit: mm)

Ordering Information

To order ZHX1010 (formerly Calibre CHX1010), use ZiLOG part number ZHX1010MV115THTR.

Notes: In order to ensure the lowest possible lead times, ZiLOG uses two different fab sources for the transceiver IC. Both of these ICs have been extensively tested and qualified to meet the ZHX1010 SIR transceiver specifications.



14

Customer Feedback Form

If you experience any problems while operating the ZHX1010 SIR transceiver, or if you note any inaccuracies while reading this product specification, please copy and complete this form, then mail or fax it to ZiLOG (see "Return Information," below). We also welcome your suggestions!

Customer Information

| Name | Country |
|----------------|---------|
| Company | Phone |
| Address | Fax |
| City/State/Zip | email |

Product Information

| Serial # or Board Fab #/Rev # |
|--------------------------------|
| Software Version |
| Document Number |
| Host Computer Description/Type |

Return Information

ZiLOG System Test/Customer Support 532 Race Street San Jose, CA 95126-3432 Fax: (408) 558-8300

Email: tools@zilog.com

Problem Description or Suggestion

| Provide a complete description of the problem or your suggestion. If you are reporting a specific problem, include all steps leading up to the occurrence of the problem. Attach additional pages as necessary. | а |
|---|---|
| | |